

# SOT847-2

plastic ball grid array package; 420 balls; body 23 x 23 x 1.55 mm

5 March 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA420
<b>Package type industry code</b>	BGA420
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	144E
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	16-03-2005
<b>Manufacturer package code</b>	SOT847

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	22.8	23	23.2	mm
package width	22.8	23	23.2	mm
seated height	-	2.25	2.25	mm
package height	1.4	1.55	1.65	mm
actual quantity of termination	-	420	-	



2 Package outline

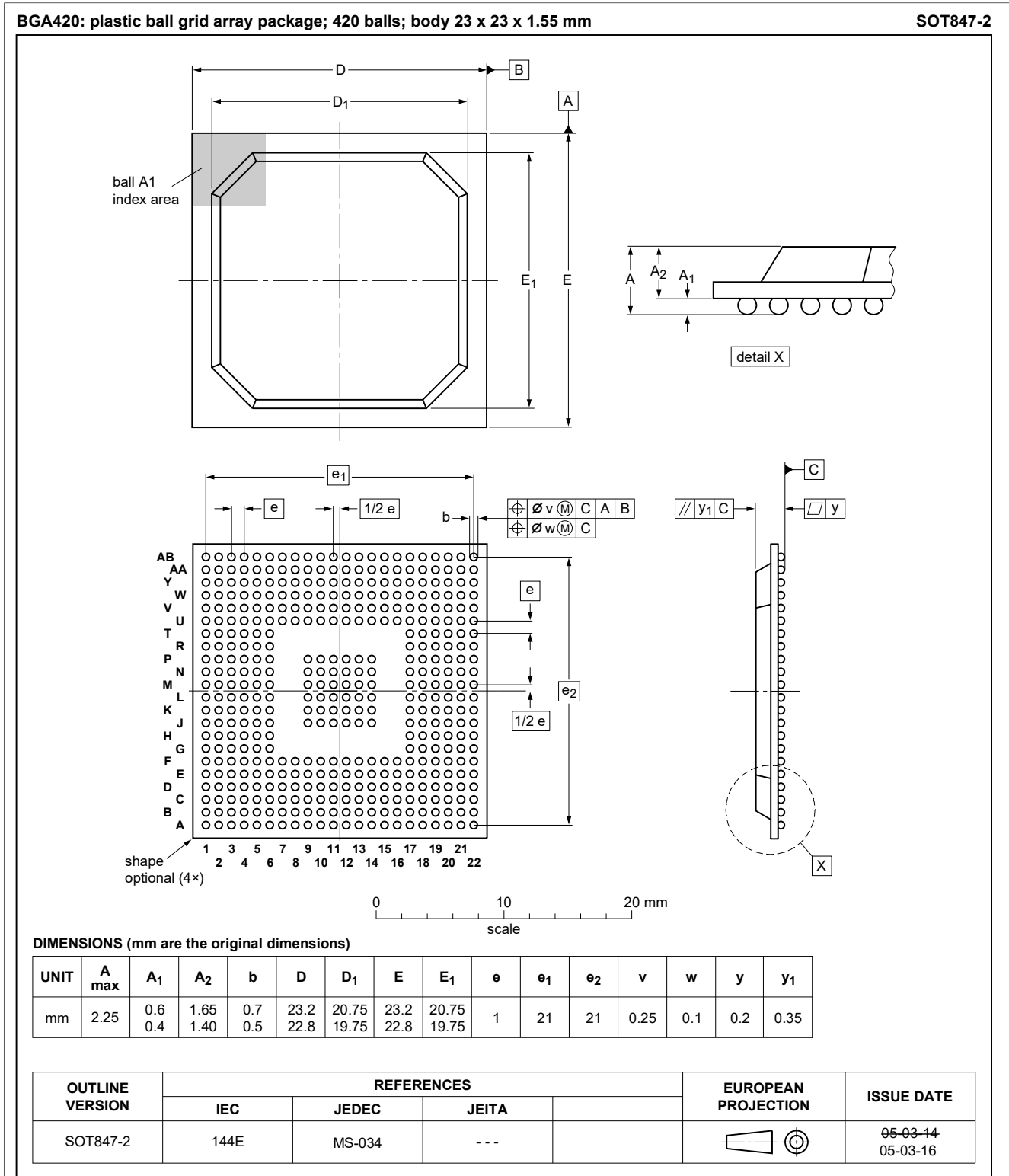


Figure 1. Package outline BGA420 (SOT847-2)

### 3 Soldering

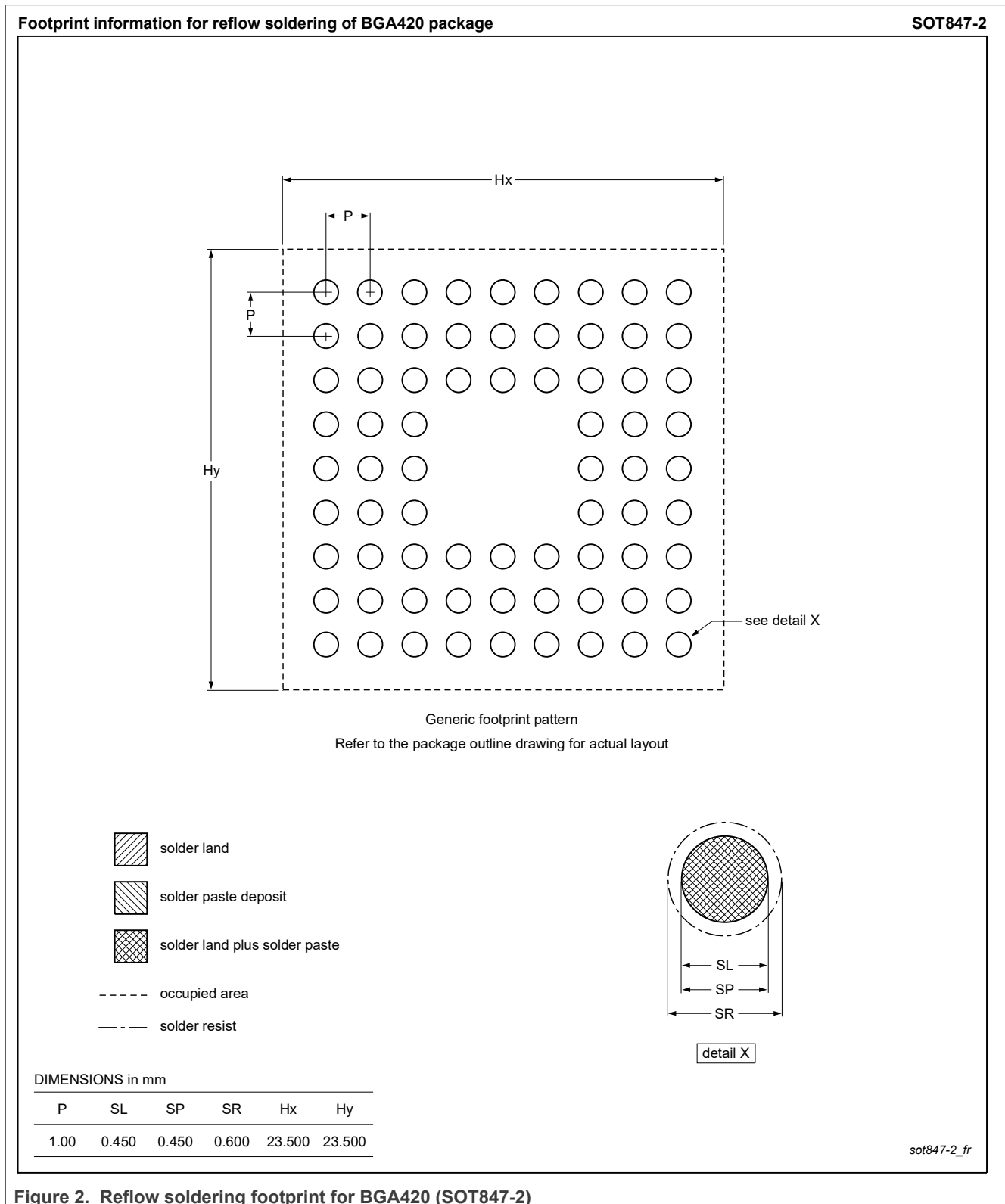


Figure 2. Reflow soldering footprint for BGA420 (SOT847-2)

## 4 Legal information

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